

Amphenol Information Communications and Commercial Products

≣FCi Basics

Amphenol ICC

BergStak HS™ 0.80mm connector Contents



- Value Proposition
- Product Overview
- Product Specifications
- Features & Benefits
- Part Numbers
- Market Applications

Value Proposition BergStak HS™ 0.80mm connector



- BergStak HS™ 0.80mm connector is a flexible solution designed for high speed and high density, parallel board-to-board applications.
- BergStak® HS™ 0.80mm support with higher speed up to 32Gb/s.
- The connector is currently offered in 120 positions and 5mm stack height. Stack heights of 5mm and 12mm with 40 to 140 pos are available upon request.
- It meets and exceeds SAS 4.0, and PCIe Gen 5 standards.
- The unique Scoop-proof housing feature of BergStak HS™ 0.80mm prevents reverse mating preventing terminal damage.
- Thanks to all these features, BergStak HS™ 0.80mm is Ideal for applications in the Communications, Data and Industrial & Instrumentation, Medical.

BergStak HS™ 0.80mm connector Product Overview





Receptacle Overview



Header Overview

Product Specifications

BergStak HS™ 0.80mm connector



Performance Characteristics

Durability: 100 cycles

Mating Force: 0.9N max . per contact

Un-mating Force: 0.1N min. per contact

Current Rating: 0.8A per contact

Voltage Rating: 100VAC

Low-level Contact Resistance LLCR : 50mΩ max.

Insulation Resistance: 1000 MΩ min.

Materials

Housing: Glass filled LCP (UL94V-0)

Terminal base metal

Receptacles: Copper Alloy

Headers: Copper Alloy

Environmental

High temperature life: 125°C for 96 hours

Humidity: 90-95% relative for 240 hours

Technical Documents

Product Spec.: GS-12-1499

Features and Benefits

BergStak HS™ 0.80mm connector

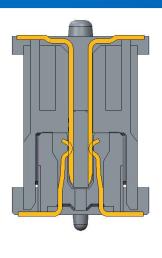


Features	Benefits		
Date rate: 24Gb/s and 32Gb/s	Meets SAS4.0 and PCIe Gen5 standard		
120 positions, with options 40 to 140 5mm stack height, with options for 5mm and 12mm	Supports a wide range of applications		
Vertical mating configuration	Suitable for parallel board stacker applications		
0.80mm double-row contact pitch	Small form factor high density layout saves board space		
Scoop-proof housings	Prevents terminal mating damage		
UL94V-0 high temperature LCP material	High flammability rating		
Locating pegs option available	Enables easy manual assembly		
Halogen-free products	Aid efforts to minimize the use of environmentally sensitive materials in the electronics industry		
Lead-Free and RoHS compliant	Meets environmental, health and safety requirements		

Design Features

BergStak HS™ 0.80mm





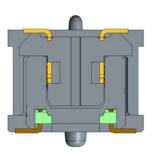
V.S.

Bergstak® 0.8mm pitch structure uses Blade on beam design.

Open Pin fill design structure to support PCIe Gen 3 or below performance.

Width 6.0mm(P1/P2/P3/P4/R1) or width 6.4mm(R2/R3/R4)

All ground pins are separated.



BergStak HS[™] product supports up to PCIe 5.0 – 32Gbps and SAS 4.0-24G by widen the tongue of the product. This is also backward compatible with existing BergStak® product's PCB(the existing PCB with ground vias on both side of GND pad).

Open pin filed design

Width 6.5mm(P1/R1).

All ground pins are separated.

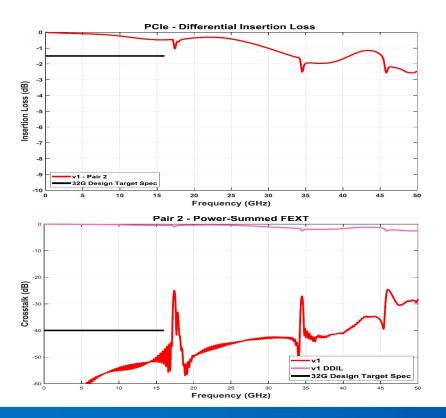
Performance

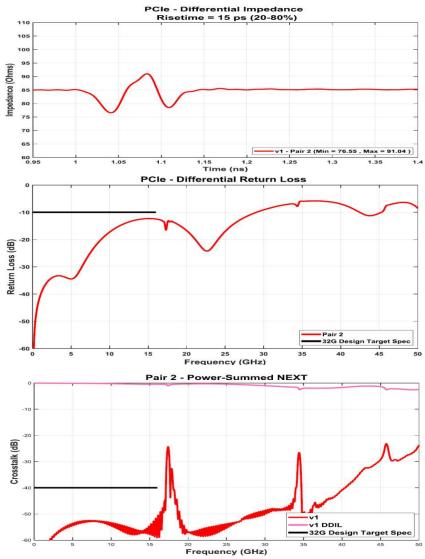
BergStak HS™ 0.80mm connector



Add a graph where we show our 5mm HS product.
 Double GND for PCIe Gen5

 Single GND for PCIe Gen 5 is achievable by using one line for signal transmission





BergStak HS™ 0.80mm connector Part Numbers



Item	Position	Product Height (mm)	Stack Height (mm)	Part Number
0.8mm BTB Vertical Header	120	4.15	5	10147614- 121406LF
0.8mm BTB Vertical Receptacle	120	3.7	5	10147613- 121406LF

Markets and Applications

BergStak HS™ 0.80mm connector



Datacom/Telecom

- Server
- Storage



Industrial and Instrumentation

- Embedded Computer
- Test and Measurement Equipment

Medical Devices

- MRI Machines
- High Definition Scopes



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THANK YOU!